

# MCUXSDKQN9090RN

## MCUXpresso SDK Release Notes for QN9090

Rev. 10 — 11 February 2025

Release notes

### Document information

Information	Content
Keywords	MCUXSDKQN9090RN, Release Notes, QN9090
Abstract	This document describes the MCUXpresso SDK release notes for QN9090.



1 Overview

The MCUXpresso SDK is a comprehensive software enablement package designed to simplify and accelerate application development with Arm Cortex-M-based devices from NXP, including its general purpose, crossover and Bluetooth-enabled MCUs. MCUXpresso SW and Tools for DSC further extends the SDK support to current 32-bit Digital Signal Controllers. The MCUXpresso SDK includes production-grade software with integrated RTOS (optional), integrated enabling software technologies (stacks and middleware), reference software, and more.

In addition to working seamlessly with the MCUXpresso IDE, the MCUXpresso SDK also supports and provides example projects for IAR, Keil, and GCC with Cmake. Support for the MCUXpresso Config Tools allows easy cloning of existing SDK examples and demos, allowing users to leverage the existing software examples provided by the SDK for their own projects.

Underscoring our commitment to high quality, the MCUXpresso SDK is MISRA-compliant and checked with Coverity static analysis tools. For details on MCUXpresso SDK, see [MCUXpresso-SDK: Software Development Kit for MCUXpresso](#).

2 MCUXpresso SDK

As part of the MCUXpresso software and tools, MCUXpresso SDK is the evolution of Kinetis SDK, includes support for LPC, DSC, and i.MX System-on-Chip (SoC). The same drivers, APIs, and middleware are still available with support for Kinetis, LPC, DSC, and i.MX silicon. The MCUXpresso SDK adds support for the MCUXpresso IDE, an Eclipse-based toolchain that works with all MCUXpresso SDKs. Easily import your SDK into the new toolchain to access to all of the available components, examples, and demos for your target silicon. In addition to the MCUXpresso IDE, support for the MCUXpresso Config Tools allows easy cloning of existing SDK examples and demos, allowing users to leverage the existing software examples provided by the SDK for their own projects.

In order to maintain compatibility with legacy Freescale code, filenames, and source code in MCUXpresso SDK containing the legacy Freescale prefix FSL has been left as is. The FSL prefix has been redefined as the NXP Foundation Software Library.

3 Development tools

The MCUXpresso SDK was compiled and tested with these development tools:

- IAR Embedded Workbench for Arm version 9.60.2
- MCUXpresso IDE version 11.10.0
- Python 3 (Used by IAR and MCUXpresso IDE post build script, and the version should be newer than 3.2)
- GNU Tools for Arm Embedded Processors 8-2018-q4-major

4 Supported development systems

This release supports boards and devices listed in [Table 1](#). The boards and devices in bold were tested in this release.

Table 1. Supported MCU devices and development boards

Development boards	MCU devices
QN9090 DK6 V3	QN9090

## 5 What is new

### MCUXpresso SDK QN9090 2.6.16

This new release package for the QN9090 platform corresponds to the SDK 2.6.16 version of the program. Compared to previous SDK 2.6.15 release, this package provides several fixes and performance improvements, detailed as below.

Here are the changes since the SDK 2.6.15 release:

- **Framework**
  - Add API to handle DCDC output change based on the VBAT value for the high-power parts (041A/AM)
- **SDK**
  - Add new feature macro to distinguish whether the `GPADC_CTRL0_GPADC_TSAMP` control bit is on the device
  - Add new variable `extendSampleTimeNumber` to indicate the ADC extend sample time
  - Fix the bug that incorrectly sets the `PASS_ENABLE` bit based on the sample time setting
  - Fix DCDC 1v3 setting of Full Force Cycle bit
- **Bluetooth Controller**
  - No updates
- **Bluetooth Host**
  - No updates
- **Bluetooth LE Application examples improvements**
  - No updates

## 6 Release contents

[Table 2](#) provides an overview of the MCUXpresso SDK release package contents and locations.

Table 2. Release contents

Deliverable	Location
Boards	<install_dir>/boards
CMSIS Arm Cortex®-M header files, DSP library source	<install_dir>/CMSIS
Demo applications	<install_dir>/boards/<board_name>/demo_apps
Documentation	<install_dir>/docs
Driver examples	<install_dir>/boards/<board_name>/driver_examples
Driver, SoC header files, extension header files and feature header files, utilities	<install_dir>/devices/<device_name>
Peripheral Drivers	<install_dir>/devices/<device_name>/drivers
RTOS examples	<install_dir>/boards/<board_name>/rtos_examples
RTOS Kernel Code	<install_dir>/rtos
Tools	<install_dir>/tools
Utilities such as debug console	<install_dir>/devices/<device_name>/utilities

## 7 MCUXpresso SDK release package

The MCUXpresso SDK release package content is aligned with the silicon subfamily it supports. This includes the boards, CMSIS, devices, documentation, middleware, and RTOS support.

### 7.1 Device support

The device folder contains the whole software enablement available for the specific System-on-Chip (SoC) subfamily. This folder includes clock-specific implementation, device register header files, device register feature header files, CMSIS derived device SVD, and the system configuration source files. Included with the standard SoC support are folders containing peripheral drivers, toolchain support, and a standard debug console.

The device-specific header files provide a direct access to the microcontroller peripheral registers. The device header file provides an overall SoC memory mapped register definition. The folder also includes the feature header file for each peripheral on the microcontroller.

The toolchain folder contains the startup code and linker files for each supported toolchain. The startup code is a CMSIS compliant startup code that efficiently transfers the code execution to the `main()` function.

#### 7.1.1 Board support

The boards folder provides the board-specific demo applications, driver examples, RTOS, and middleware examples.

#### 7.1.2 Demo applications and other examples

The demo applications demonstrate the usage of the peripheral drivers to achieve a system level solution. Each demo application contains a *readme* file that describes the operation of the demo and required setup steps.

The driver examples demonstrate the capabilities of the peripheral drivers. Each example implements a common use case to help demonstrate the driver functionality.

## 7.2 Wireless

The following connectivity-supporting documentation is included in the documentation package:

- *Bluetooth Low Energy Host Stack API Reference Manual*
- *Bluetooth Low Energy Application Developer's Guide*
- *Bluetooth Low Energy Demo Applications User's Guide*
- *Bluetooth Low Energy Host Stack FSCI Reference Manual*
- *Connectivity Framework Reference Manual*

### 7.2.1 Bluetooth LE software

This version corresponds to the QPATCH1 build of the QN9090 Bluetooth LE Software. The Bluetooth LE v5.0 features in this release have undergone a Bluetooth SIG qualification listing process, as follows:

- [Launch Studio Host](#)
- [Launch Studio Controller](#)

## 7.3 Middleware

### 7.3.1 RTOS

The MCUXpresso SDK is integrated with FreeRTOS OS.

### 7.3.2 Other middleware

Optional middleware packages can be included in the release based on the user selection. See `<install_dir>/SW-Content-Register.txt` for a list of components and associated licenses.

## 8 Known issues

The following are the known issues, limitations, or workarounds.

### 8.1 Maximum file path length in Windows 7<sup>®</sup> operating system

The Windows 7 operating system imposes a 260-character maximum length for file paths. When installing the MCUXpresso SDK, place it in a directory close to the root to prevent file paths from exceeding the maximum character length specified by the Windows operating system. The recommended location is the `C:\nxp` folder.

### 8.2 New project wizard compile failure

The following components request the user to manually select other components that they depend upon in order to compile. These components depend on several other components and the New Project Wizard (NPW) is not able to decide which one is needed by the user.

**Note:** *xxx means core variants, such as, cm0plus, cm33, cm4, cm33\_nodsp.*

Also for low-level adapter components, currently the different types of the same adapter cannot be selected at the same time. For example, if there are two types of timer adapters, `gpt_adapter` and `pit_adapter`, only one can be selected as timer adapter in one project at a time. Duplicate implementation of the function results in an error.

### 8.3 CMSIS PACK new project compile failure

The generated configuration cannot be applied globally. The components, `serial_manager_usb_cdc_virtual` and `serial_manager_usb_cdc_virtual_xxx` (*xxx means core variants like cm0plus, cm33, cm4, and cm33\_nodsp*) are unsupported for new project wizard of CMSIS pack and will lead to compile failure if selected while creating new project(s).

### 8.4 Other limitations

- FreeRTOS tickless mode configuration may exhibit stability issues. An update will be available in an upcoming maintenance release.
- There's a compiling issue while creating the project in MCUXpresso without selecting the board. To fix this issue, add `board_utility.h` to the project manually.
- Using `malloc` from `libc` (and related functions) is not supported. This action collides with the allocator based on the `pvHeap` functions (they use the same memory area). None of the standard SDK apps uses `malloc`. If the need arises to use `malloc` in a customer application, use a mechanism similar to the wrapping described at [linux.org/docs/man1/ld.html](https://linux.org/docs/man1/ld.html).

## 9 About the ROM patch

The current release of the ROM patch is version 5. Devices may be released from stock with an older version of the ROM patch. When using the DK6 CLI Flash Programmer, this will be indicated by the message **WARNING: Bootloader in device is out of date. See application note JN-AN-1263 or contact support for update information.** To install the current release of the ROM patch, download the *JN5189/QN9090/K32W061 ROM Patch* (document [JN-AN-1263](#)) and follow the instructions there.

## 10 Revision history

[Table 3](#) summarizes the revisions to this document.

Table 3. Revision history

Document ID	Release date	Description
MCUXSDKQN9090RN v.10	11 February 2025	Updated for MCUXpresso SDK 2.6.16 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.9	22 July 2024	Updated for MCUXpresso SDK 2.6.15 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.8	23 April 2024	Updated for MCUXpresso SDK 2.6.14 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.7	01 November 2023	Updated for MCUXpresso SDK 2.6.13 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.6	07 July 2023	Updated for MCUXpresso SDK 2.6.12 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.5	21 April 2023	Updated for MCUXpresso SDK 2.6.11 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.4	06 February 2023	Updated for MCUXpresso SDK 2.6.10 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.3	16 December 2022	Updated for MCUXpresso SDK 2.6.9 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.2	09 November 2022	Updated for MCUXpresso SDK 2.6.8 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.1	4 March 2022	Updated for MCUXpresso SDK 2.6.5 release <ul style="list-style-type: none"><li>Updated <a href="#">Section 3 "Development tools"</a></li><li>Updated <a href="#">Section 5 "What is new"</a></li></ul>
MCUXSDKQN9090RN v.0	6 August 2021	Initial release for MCUXpresso SDK 2.6.4 release

## Legal information

### Definitions

**Draft** — A draft status on a document indicates that the content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included in a draft version of a document and shall have no liability for the consequences of use of such information.

### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

**Terms and conditions of commercial sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <https://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

**Suitability for use in non-automotive qualified products** — Unless this document expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

**HTML publications** — An HTML version, if available, of this document is provided as a courtesy. Definitive information is contained in the applicable document in PDF format. If there is a discrepancy between the HTML document and the PDF document, the PDF document has priority.

**Translations** — A non-English (translated) version of a document, including the legal information in that document, is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

**Security** — Customer understands that all NXP products may be subject to unidentified vulnerabilities or may support established security standards or specifications with known limitations. Customer is responsible for the design and operation of its applications and products throughout their lifecycles to reduce the effect of these vulnerabilities on customer's applications and products. Customer's responsibility also extends to other open and/or proprietary technologies supported by NXP products for use in customer's applications. NXP accepts no liability for any vulnerability. Customer should regularly check security updates from NXP and follow up appropriately.

Customer shall select products with security features that best meet rules, regulations, and standards of the intended application and make the ultimate design decisions regarding its products and is solely responsible for compliance with all legal, regulatory, and security related requirements concerning its products, regardless of any information or support that may be provided by NXP.

NXP has a Product Security Incident Response Team (PSIRT) (reachable at [PSIRT@nxp.com](mailto:PSIRT@nxp.com)) that manages the investigation, reporting, and solution release to security vulnerabilities of NXP products.

**NXP B.V.** — NXP B.V. is not an operating company and it does not distribute or sell products.

### Trademarks

Notice: All referenced brands, product names, service names, and trademarks are the property of their respective owners.

**NXP** — wordmark and logo are trademarks of NXP B.V.

**Amazon Web Services, AWS, the Powered by AWS logo, and FreeRTOS** — are trademarks of Amazon.com, Inc. or its affiliates.

**AMBA, Arm, Arm7, Arm7TDMI, Arm9, Arm11, Artisan, big.LITTLE, Cordio, CoreLink, CoreSight, Cortex, DesignStart, DynamIQ, Jazelle, Keil, Mali, Mbed, Mbed Enabled, NEON, POP, RealView, SecurCore, Socrates, Thumb, TrustZone, ULINK, ULINK2, ULINK-ME, ULINK-PLUS, ULINKpro, µVision, Versatile** — are trademarks and/or registered trademarks of Arm Limited (or its subsidiaries or affiliates) in the US and/or elsewhere. The related technology may be protected by any or all of patents, copyrights, designs and trade secrets. All rights reserved.

**Bluetooth** — the Bluetooth wordmark and logos are registered trademarks owned by Bluetooth SIG, Inc. and any use of such marks by NXP Semiconductors is under license.

**IAR** — is a trademark of IAR Systems AB.

**Kinetis** — is a trademark of NXP B.V.

**Matter, Zigbee** — are developed by the Connectivity Standards Alliance. The Alliance's Brands and all goodwill associated therewith, are the exclusive property of the Alliance.



## Contents

---

<b>1</b>	<b>Overview .....</b>	<b>2</b>
<b>2</b>	<b>MCUXpresso SDK .....</b>	<b>2</b>
<b>3</b>	<b>Development tools .....</b>	<b>2</b>
<b>4</b>	<b>Supported development systems .....</b>	<b>2</b>
<b>5</b>	<b>What is new .....</b>	<b>3</b>
<b>6</b>	<b>Release contents .....</b>	<b>3</b>
<b>7</b>	<b>MCUXpresso SDK release package .....</b>	<b>4</b>
7.1	Device support .....	4
7.1.1	Board support .....	4
7.1.2	Demo applications and other examples .....	4
7.2	Wireless .....	4
7.2.1	Bluetooth LE software .....	4
7.3	Middleware .....	5
7.3.1	RTOS .....	5
7.3.2	Other middleware .....	5
<b>8</b>	<b>Known issues .....</b>	<b>5</b>
8.1	Maximum file path length in Windows 7® operating system .....	5
8.2	New project wizard compile failure .....	5
8.3	CMSIS PACK new project compile failure .....	5
8.4	Other limitations .....	5
<b>9</b>	<b>About the ROM patch .....</b>	<b>6</b>
<b>10</b>	<b>Revision history .....</b>	<b>6</b>
	<b>Legal information .....</b>	<b>7</b>

---

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

---